

# VRFA0021 - BD



## DC-45GHz GaAs MMIC Wideband Amplifier

Preliminary Datasheet v2

### Features

- Frequency Range: DC to 45GHz
- P1dB Output Power 15.5dBm CW
- Small Signal Gain 12dB
- Bias:  $V_d = 8V$ ,  $I_{dq} = 50mA$
- Die Size: 2.5mm x 0.77mm x 0.1 mm



### Description

The VRFA0021-BD is a wideband GaAs MMIC amplifier which operates over the frequency range of DC to 45GHz. The amplifier typically delivers a small signal gain of +12dB, output power P1dB of +15.5dBm. The VRFA0021-BD draws 50mA from a +8VDC supply. The RF ports are DC blocked and matched to 50Ω. Typical applications for the VRFA0021-BD include EW systems, radar and Test and Instrumentation.

### Electrical Specifications

$T = +25^{\circ}C$  baseplate,  $V_{DD} = +8V$ ,  $I_{dq} = 50mA$

Parameter	Specification			Unit
	Max.	Typ.	Min.	
Frequency Bandwidth	DC		45	GHz
Small Signal Gain		12		dB
I/P Return Loss		-12		dB
O/P Return Loss		-12		dB
Noise Figure		2 @ 12GHz		dB
P1dB Output Power		15.5		dBm

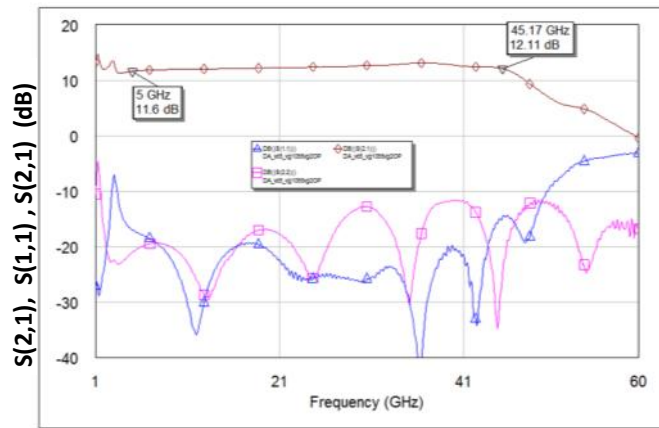
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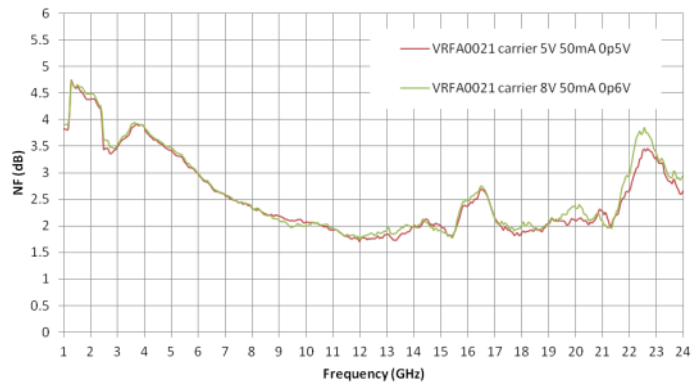
### Measured Performance (on wafer)

$T=+25^{\circ}\text{C}$  baseplate,  $V_{DD} = +8\text{V}$ ,  $I_{dq}=0.35\text{A}$

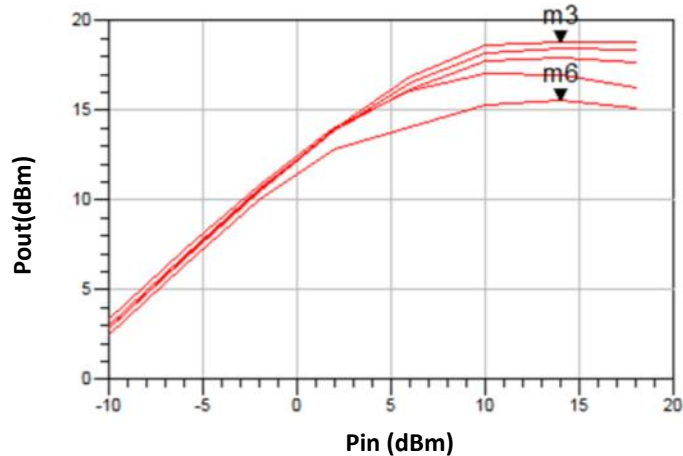
Gain, Return Loss



Noise Figure (dB) versus bias point



Power Sweep (simulated)



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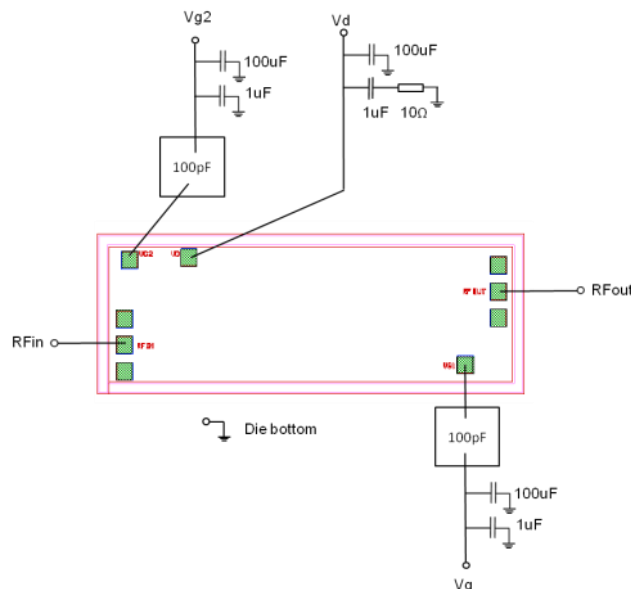
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### Recommended Absolute Maximum Ratings <sup>[1]</sup>

Parameter	Symbol	Value	Notes
Drain Bias Voltage	$V_d$	+10V	
Gate Bias Voltage	$V_g$	-5V	
Gate Current	$I_g$	5mA	
RF input power	$RF_{in}$	+5dBm	
Power Dissipation	$P_d$		Related to Junction Temperature
Junction Temperature	$T_j$	200°C	For maximum median device lifetime, $T_j$ should be minimised
Storage Temperature	$T_{storage}$	-55 to 150°C	

<sup>[1]</sup> Operation outside these conditions may cause permanent damage to the device. Combination of maximum rating conditions may reduce the values. Device performance at these ratings is not implied.

### Assembly & Bonding Diagram



Die Size	2.5mm x 0.77mm
Die Thickness	50μm
Minimum Bondpad opening	70μm x 70μm

Minimal length (0.15nH) are recommended for RF bondwires. The RF input and output ports are DC blocked.

GaAs devices are ESD sensitive and precautions should be observed during storage, handling, assembly and testing.

